

SKR 5,6 Qu bond



DIODE

$I_F(DC) = 50 \text{ A}$

$V_{RRM} = 1600 \text{ V}$

Size: 5,6 mm x 5,6 mm

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Features

- high current density due to mesa technology
- high surge current
- compatible to thick wire bonding
- compatible to all standard solder processes

Typical Applications*

- uncontrolled rectifier bridges

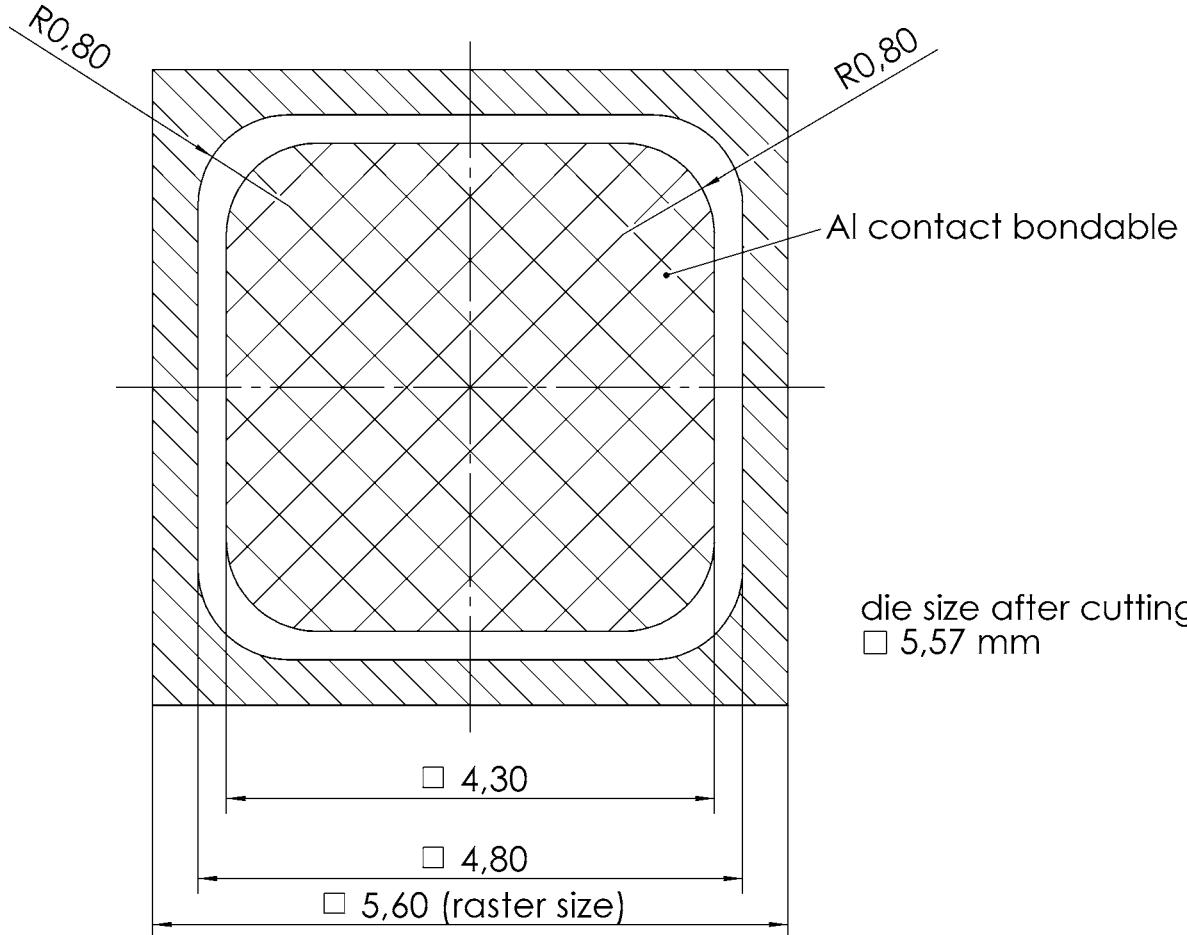
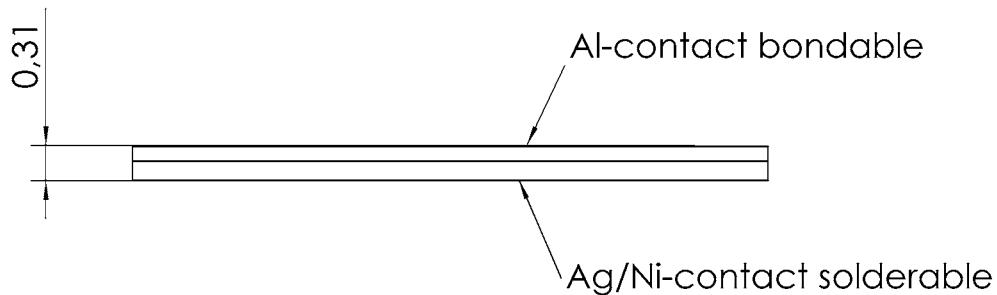
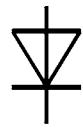
Absolute Maximum Ratings		Values	Unit	
Symbol	Conditions			
V_{RRM}	$T_j = 25^\circ\text{C}, I_R = 0.05 \text{ mA}$	1600	V	
$I_F(AV)$	$T_s = 80^\circ\text{C}, T_j = 150^\circ\text{C}$	40	A	
i^2t	$T_j = 150^\circ\text{C}, 10 \text{ ms, sin } 180^\circ$	1200	A^2s	
I_{FSM}	10 ms $\text{sin } 180^\circ$	$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	635 490	A A
T_{jmax}		150	$^\circ\text{C}$	

Electrical Characteristics		min.	typ.	max.	Unit
Symbol	Conditions				
I_R	$T_j = 25^\circ\text{C}, V_{RRM}$			0.05	mA
	$T_j = 145^\circ\text{C}, V_{RRM}$			1.1	mA
V_F	$T_j = 25^\circ\text{C}, I_F = 25 \text{ A}$	1	1.21	V	
	$T_j = 125^\circ\text{C}, I_F = 25 \text{ A}$	0.9	1.1	V	
$V_{(TO)}$	$T_j = 125^\circ\text{C}$			0.83	V
r_T	$T_j = 125^\circ\text{C}$			6.2	$\text{m}\Omega$
t_{rr}	$T_j = 25^\circ\text{C}, \pm 1 \text{ A}$		22		μs

Thermal Characteristics		min.	typ.	max.	Unit
Symbol	Conditions				
T_j		-40	150	$^\circ\text{C}$	
T_{stg}		-40	150	$^\circ\text{C}$	
T_{solder}	10 min.			250	$^\circ\text{C}$
T_{solder}	5 min.			320	$^\circ\text{C}$
$R_{th(j-s)}$	soldered on 0,38 mm DCB, reference point on copper heatsink close to the chip		1.2		K/W

Mechanical Characteristics		Values	Unit
Symbol	Conditions		
Raster size		5.6 x 5.6	mm^2
Area total		31.36	mm^2
Anode		bondable (Al)	
Cathode		solderable (Ag/Ni)	
Wire bond		Al, diameter $\leq 500 \mu\text{m}$	
Package		wafer frame	
Chips / Package		470	pcs





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.